

## **ABSTRACT**

### **PROCESSING METHOD FOR WAFER**

A processing method for a wafer in which a front surface of the wafer is sealed with a sealing member and a plurality of bumps are formed individually in the chip regions of the sealing member includes an alignment step of picking up an image of a front surface side of the wafer through the sealing member by the visible light image pickup unit from the front surface side of the wafer to detect alignment marks and detecting a scheduled division line to be laser processed based on the alignment marks, and a division step of irradiating a laser beam of a wavelength, which is absorbed by the sealing member and the wafer, along the scheduled division line from the front surface side of the wafer to divide the wafer into individual device chips sealed at the front surface thereof with the sealing member by ablation processing. The alignment step is carried out while light is irradiated in an oblique direction upon a region, whose image is to be picked up by the visible light image pickup unit, by an oblique light unit.

(Figure 4)